20 V, 4.0 A, Low V_{CE(sat)} PNP Transistor

ON Semiconductor's e²PowerEdge family of low $V_{CE(sat)}$ transistors are miniature surface mount devices featuring ultra low saturation voltage ($V_{CE(sat)}$) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical applications are DC–DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

• This is a Pb-Free Device

MAXIMUM RATINGS (T_A = 25°C)

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V _{CEO}	-20	Vdc
Collector-Base Voltage	V _{CBO}	-20	Vdc
Emitter-Base Voltage	V _{EBO}	-7.0	Vdc
Collector Current - Continuous	Ic	-2.0	Α
Collector Current - Peak	I _{CM}	-4.0	Α

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation T _A = 25°C Derate above 25°C	P _D (Note 1)	460 3.7	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 1)	270	°C/W
Total Device Dissipation T _A = 25°C Derate above 25°C	P _D (Note 2)	540 4.3	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 2)	230	°C/W
Total Device Dissipation (Single Pulse < 10 sec.)	P _{Dsingle} (Note 3)	710	mW
Junction and Storage Temperature Range	T _J , T _{stg}	–55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

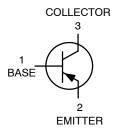
- 1. FR-4 @ 100 mm², 1 oz. copper traces.
- 2. FR-4 @ 500 mm², 1 oz. copper traces.
- 3. Thermal response.



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$\begin{array}{c} -20 \text{ VOLTS} \\ 4.0 \text{ AMPS} \\ \text{PNP LOW V}_{\text{CE(sat)}} \text{ TRANSISTOR} \\ \text{EQUIVALENT R}_{\text{DS(on)}} \text{ 65 m} \Omega \end{array}$





CASE 318 STYLE 6

DEVICE MARKING



VC = Specific Device Code

M = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)
*Date Code orientation and/or overbar may
vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]		
NSS20200LT1G	SOT-23 (Pb-Free)	3000/Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage $(I_C = -10 \text{ mAdc}, I_B = 0)$	V _(BR) CEO	-20	-	-	Vdc
Collector – Base Breakdown Voltage $(I_C = -0.1 \text{ mAdc}, I_E = 0)$	V _(BR) CBO	-20	-	-	Vdc
Emitter – Base Breakdown Voltage $(I_E = -0.1 \text{ mAdc}, I_C = 0)$	V _{(BR)EBO}	-7.0	-	-	Vdc
Collector Cutoff Current $(V_{CB} = -20 \text{ Vdc}, I_E = 0)$	I _{CBO}	_	-	-0.1	μAdc
Emitter Cutoff Current (V _{EB} = -7.0 Vdc)	I _{EBO}	I	-	-0.1	μAdc
ON CHARACTERISTICS					
DC Current Gain (Note 4) $ (I_C = -1.0 \text{ mA}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -500 \text{ mA}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -1.0 \text{ A}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -2.0 \text{ A}, V_{CE} = -2.0 \text{ V}) $	h _{FE}	250 250 180 150	- 300 - -	- - - -	
Collector – Emitter Saturation Voltage (Note 4) $ \begin{pmatrix} I_C = -0.1 \text{ A, } I_B = -0.010 \text{ A} \end{pmatrix} \text{ (Note 5)} \\ \begin{pmatrix} I_C = -1.0 \text{ A, } I_B = -0.100 \text{ A} \end{pmatrix} \\ \begin{pmatrix} I_C = -1.0 \text{ A, } I_B = -0.010 \text{ A} \end{pmatrix} \\ \begin{pmatrix} I_C = -2.0 \text{ A, } I_B = -0.200 \text{ A} \end{pmatrix} $	V _{CE(sat)}	- - -	-0.008 -0.065 -0.100 -0.130	-0.013 -0.090 -0.120 -0.180	V
Base – Emitter Saturation Voltage (Note 4) $(I_C = -1.0 \text{ A}, I_B = -0.1 \text{ A})$	V _{BE(sat)}	-	-	-0.900	V
Base – Emitter Turn–on Voltage (Note 4) (I _C = -1.0 A, V _{CE} = -2.0 V)	V _{BE(on)}	_	-	-0.900	V
Cutoff Frequency ($I_C = -100 \text{ mA}$, $V_{CE} = -5.0 \text{ V}$, $f = 100 \text{ MHz}$)	f _T	100	-	-	MHz
Input Capacitance (V _{EB} = 0.5 V, f = 1.0 MHz)	Cibo	-	-	330	pF
Output Capacitance (V _{CB} = 3.0 V, f = 1.0 MHz)	Cobo	-	-	100	pF
SWITCHING CHARACTERISTICS					
Delay ($V_{CC} = -15 \text{ V}, I_C = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$)	t _d	=	-	60	ns
Rise ($V_{CC} = -15 \text{ V}, I_C = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$)	t _r	-	-	120	ns
Storage ($V_{CC} = -15 \text{ V}, I_C = 750 \text{ mA}, I_{B1} = 15 \text{ mA}$)	t _s	_	-	300	ns
Fall (V _{CC} = -15 V, I _C = 750 mA, I _{B1} = 15 mA)	t _f	-	-	130	ns

^{4.} Pulsed Condition: Pulse Width = 300 msec, Duty Cycle ≤ 2%.
5. Guaranteed by design but not tested.

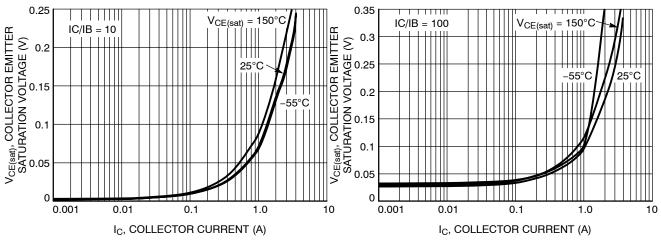


Figure 1. Collector Emitter Saturation Voltage vs. Collector Current

Figure 2. Collector Emitter Saturation Voltage vs. Collector Current

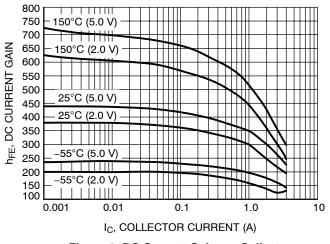


Figure 3. DC Current Gain vs. Collector Current

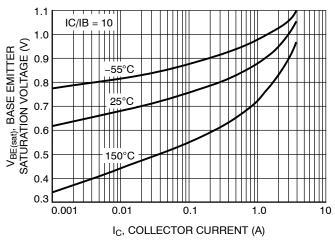


Figure 4. Base Emitter Saturation Voltage vs. Collector Current

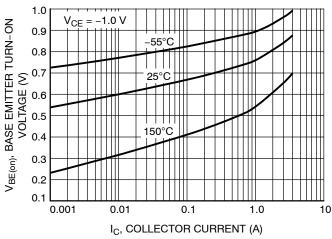


Figure 5. Base Emitter Turn-On Voltage vs.
Collector Current

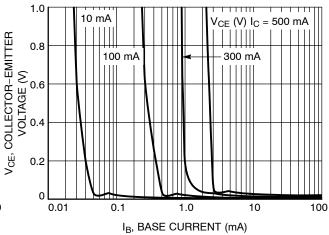
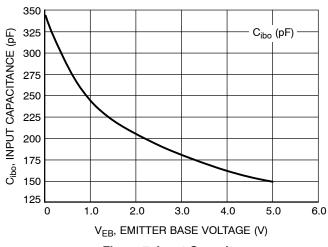


Figure 6. Saturation Region



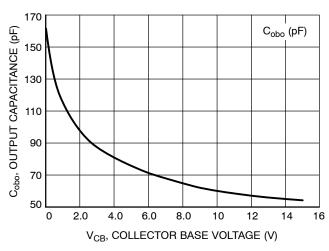


Figure 7. Input Capacitance

Figure 8. Output Capacitance

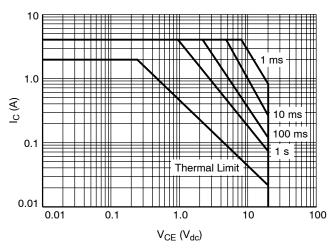
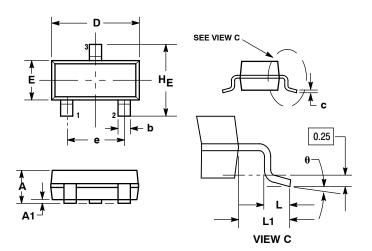


Figure 9. Safe Operating Area

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AN**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF
- BASE MATERIAL. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

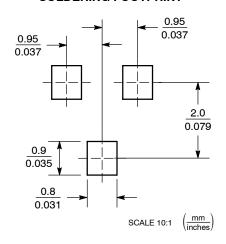
	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.89	1.00	1.11	0.035	0.040	0.044	
A1	0.01	0.06	0.10	0.001	0.002	0.004	
b	0.37	0.44	0.50	0.015	0.018	0.020	
С	0.09	0.13	0.18	0.003	0.005	0.007	
D	2.80	2.90	3.04	0.110	0.114	0.120	
E	1.20	1.30	1.40	0.047	0.051	0.055	
е	1.78	1.90	2.04	0.070	0.075	0.081	
L	0.10	0.20	0.30	0.004	0.008	0.012	
L1	0.35	0.54	0.69	0.014	0.021	0.029	
HE	2.10	2.40	2.64	0.083	0.094	0.104	

STYLE 6: PIN 1.

BASE 2. **EMITTER**

3. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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